CLAIMS

1. A power amplifier module assembly, comprising:

a power amplifier module with a flange coupled thereto;

a mounting bracket coupled to the flange and surrounding the power amplifier module;

a thermally conductive pad having an electrically conductive surface on one side for coupling to the mounting bracket and the flange so as to enclose the power amplifier module.

2. The power amplifier module assembly of claim 1, wherein the thermally conductive pad is compressibly coupled to the mounting bracket and flange via a heat sink.

3. The power amplifier module assembly of claim 2, wherein the heat sink comprises a chassis.

4. The power amplifier module assembly of claim 3, wherein the chassis comprises a radio chassis.

5. An assembly for a power amplifier module, comprising:

a flange coupled to the amplifier module;

a mounting bracket coupled to the flange and providing a fence around the power amplifier module; and

a thermally conductive pad, the thermally conductive pad having an electrically conductive surface on one side and a non-electrically conductive surface on the other side, the electrically conductive surface for coupling to the mounting bracket and flange, and the non-electrically conductive surface for coupling to a heat sink.

6. The assembly of claim 5, wherein the assembly is surface mountable.

7. The assembly of claim 6, wherein the power amplifier module has leads characterized by a lead bend that is co-planar with the mounting bracket.

8. The assembly of claim 7, wherein the power amplifier module is assembled upside down into the mounting bracket.

9. The assembly of claim 5, wherein the thermally conductive pad provides both thermal dissipation and shielding to the power amplifier module.

10. The assembly of claim 5, wherein the heat sink comprises a chassis of a communication device.

11. The assembly of claim 10, wherein the communication device comprises a radio.

12. A communication device, including:

a substrate;

a power amplifier module coupled to the substrate;

a mounting bracket coupled to the substrate and surrounding the power amplifier module;

a flange coupled to the amplifier module and the mounting bracket; and

a chassis having a thermally conductive pad coupled thereto, the thermally conductive pad having an electrically conductive surface, the electrically conductive surface for coupling to the mounting bracket and the flange so as to enclose the power amplifier module thereby providing shielding, the thermally conductive pad for transferring heat away from the flange to the chassis.

13. The communication device of claim 12, wherein the thermally conductive pad is coupled to the chassis through a non-electrically conductive surface, and the electrically conductive surface is compressibly coupled to the flange and mounting bracket.

14. The communication device of claim 12, wherein the communication device comprises a radio.